Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.012”**

**A**

**.012”**

**Top Material: Al**

**Backside Material: Au**

**Bond Pad Size: .0037”**

**Backside Potential: Cathode**

**Mask Ref:**

**APPROVED BY: DK DIE SIZE .012” X .012” DATE: 10/5/22**

**MFG: ZETEX THICKNESS .007” P/N: ZC2800**

**DG 10.1.2**

#### Rev B, 7/19/02